# semiconductor packaging news

EV Group and Dymek Form JV Company in Malaysia to Enhance Regional Support – May 25, 2023

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#### May 25, 2023

# Keeping Moore's Law Going Is Getting Complicated

There was a time, decades really, when all it took to make a better computer chip were smaller transistors and narrower interconnects. That time's long gone now, and although transistors will continue to get a bit smaller, simply making them so is no longer the point. The only way to keep up the exponential pace of computing now is a scheme called system technology co-optimization ... **IEEE Spectrum** 



Copper Stud & CTE Nano Tech Underfill AIT's proven flip-chip and BGA multi-level underfills offer both 18 ppm/°C copper CTE matching fine-pitch & nanopitch with 10 µm & 0.3 µm respective cut-off particles. AI Technology



New Packaging FA Solutions Using Correlated X-ray Microscopy, LaserFIB

New advances using LaserFIB and 3D X-ray microscopy enable targeted cross-section preparation and analysis of defects in less than five hours. Read more. **ZEISS Microscopy** 



Mystified staff members of Zeku - a fabless chip firm started in 2019 by OPPO, China's third largest smartphone company - were told on the evening of May 11 that they ... Asia Times

### Keys to Component Lead Tinning Success

The motivation behind component lead tinning is to facilitate the removal of gold plating to eliminate the risk of gold embrittlement, tin whisker mitigation, or processing ... **Technical Paper** 

# Nvidia shares spike 26% on huge forecast beat driven by A.I. chip demand

Nvidia reported first-quarter earnings for its fiscal 2024 on Wednesday, with a stronger-thanexpected forecast that drove shares up 26% in extended trading. Here's how ... CNBC

# **Technical Papers**

- Improving SiC Power Devices with Laser Ohmic Contact Formation
- Defluxing of Copper Pillar Bumped Flip-Chips
- Functional testing of 0.3mm pitch WLP
- Yacuum Fluxless Reflow Technology for Fine Pitch Interconnect Bumping Applications
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- Optimized Reflow Solder TIMs Processes for Heterogeneous Packages
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Test Your Knowledge Which US organisation's headquarters is situated in Langley, Virginia? See answer below.

# **Designing for Mil-Aero?**

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solutions, from quick-turn prototypes **QP** Technologies

# **Press Releases**

EV Group and Dymek Form JV Company in Malaysia to Enhance Regional Support EV Group (EVG) announced that they have established a new joint venture company in Malaysia. The new company, called EV Group Malaysia Dymek Sdn. Bhd., will be charged ... EV Group

# Imec and Brewer Science present process solutions for CVD oxide deposition processes at ECTC

Brewer Science, Inc. is presenting and exhibiting at Electronic Components and Technology Conference (ECTC) May 30th through June 2nd. Dr. Koen Kennes from imec is ...

Brewer Science, Inc.

# SEMI North America Advisory Board Welcomes New Members

SEMI announced the election of two new members to the SEMI North America Advisory Board (NAAB): Maheen Hamid, co-founder, CEO and COO of Breker Verification Systems ... SEMI

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tinning. Fully programmable robotic hot solder dip machines control dip depth, dwell times & temps to meet GEIA-0006 standards. **Circuit Technology Center** 

# LPDDR, NOR Flash Pairs to Meet Automotive Demands

SPI NOR flash is running out of gas, at least for automotive applications, so Infineon Technologies is pairing the proven Low-Power Double Data Rate (LPDDR) interface ... **EE Times** 

# Sustainability 101: It's Not Just Carbon - Reducing Greenhouse Gasses

The idea of semiconductor manufacturing becoming a trillion-dollar industry is astounding, exciting, or worrisome, depending on your viewpoint. Growth in the ... **3DInCites** 

### Nanya expects chip prices to stabilize next quarter

DRAM chipmaker Nanya Technology Corp said chip prices might stabilize next quarter, as improving inventory along the supply chain and industrywide production cuts ... **Taipei Times** 



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# Automotive Relationships Shifting With Chiplets

The automotive industry is in the midst of a tremendous and rapid change on many fronts. OEMs are exploring new functions and features to add to their vehicles, ... Semiconductor Engineering

# S. Korea asks US to give more leeway on chip expansion in China

South Korea has asked the United States to reconsider details of the guardrail provision of its CHIPS Act, to ease the regulations limiting Korean chipmakers from ... The Korea Herald

#### US lawmaker demands action against Chinese chip firm CXMT after Micron The US Commerce Department should put trade curbs on Chinese memory chip maker

Changxin Memory Technologies (CXMT) after Beijing banned the sale of some ... South China Morning Post

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#### Ouote of the Day

"Doubt everything or believe everything: these are two equally convenient strategies. With either we dispense with the need for reflection." Henri Poincare

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# What Year Was It?

**Constitutional Convention Convenes** With George Washington presiding, the Constitutional Convention formally convenes. The process began with the proposal of James Madison's Virginia Plan.



The day was May 25. What year was it?

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# Apple and Broadcom sign multi-year deal to develop made-in-USA chips

May 30, 2023: 2023 IEEE 73rd Electronic Components and Technology Conference

Jun 1, 2023: Overview of semiconductor manufacturing webinar for European attendees

Jun 5, 2023: Overview of semiconductor manufacturing Webinar for Asian Attendees

In a bid to diversify away from chips made in Asia, Apple announced a multi-billion-dollar multiyear deal with Broadcom to help the latter develop chips made in the US. ... Digitimes



Calendar





Cartoon of the Day

Brewer Science



"You're entitled to one week paid vacation if you bring your laptop with you and never turn off your cell phone."

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# Automated Epoxy Die Attach

With rapid time-to-market (B-8 requirements, automating the packaging process has become more critical than ever. Epoxy die attach is a consistent, reliable &



flexible form of component attach. Palomar Technologies, Inc.

Test Your Knowledge Answer

Which US organisation's headquarters is situated in Langley, Virginia? Answer: The CIA

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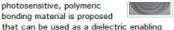
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Jeff Ferry, Publisher | Ken Cavallaro, Editor/Business Manager

May 23, 2023: SEMICON Southeast Asia 2023

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